

View Online at https://aerobasegroup.com/nsn/5910-01-330-0477

Body Style: Chip type **Reliability Indicator:** Established **Reliability Failure Rate Level In Percent:** 0.001 **Terminal Length:** Between 0.3 millimeters and 0.7 millimeters **Body Length:** 2.0 millimeters **Body Width:** 1.3 millimeters **Body Height:** 1.3 millimeters Schematic Diagram Designator: No common or grounded electrode (s) Insulation Resistance At Maximum Operating Temp: 10000.0 megohms **Capacitance Value Per Section:** 6.800 picofarads single section Nonderated Operating Temp: Between -55.0 degrees celsius and 125.0 degrees celsius Tempurature Coefficient Of Capacitance Per Section In Ppm Per Deg Celsius: 0.0 single section Nonderated Continuous Voltage Rating And Type Per Section: 100.0 dc single section **Tolerance Of Tempurature Coefficient Per Section In Ppm Per Deg Celsius:** -30.0/+30.0 single section **Tolerance Range Per Section:** -0.10/+0.10 picofarads single section **Case Material:** Ceramic Insulation Resistance At Reference Temp: 100000.0 megohms **Dissipation Factor At Reference Tempurature In Percent:** 0.150 **Terminal Surface Treatment:** Palladium and silver **Precious Material And Location:** Terminal surfaces palladium and terminal surfaces silver **Test Data Document:**

81349-mil-c-55681 specification (includes engineering type bulletins, brochures, etc., that reflect specification type data in specification format; excludes commercial catalogs, industry directories, and similar trade publications, reflecting general type data on certain environmental and performance requirements and test conditions that are shown as "typical", "average", "", etc.).



Terminal Type And Quantity:

2 bonding pad

Specification Data:

81349-mil-c-55681/7 government specification

Shelf Life:

N/a

Unit Of Measure:

Demilitarization:

No

Fiig:

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